

# EDCON-COMPONENTS



## Technical Specifications:

Temperature Range:
Rated Load:
Contact Resistance:
Insulation Resistance:
Withstanding Voltage:
Actuating Force:
Lifetime:
TEMPERATURE:
RELATIVE HUMIDITY:
HUMIDITY TEST:
HEAT TEST:
COLD TEST:
SOLDERABILITY TEST:
TEST CONDITIONS:
REFLOW SOLDERING:
MATERIAL:
F= GROUNDING SPRING
E= SHIELDING:
D= PIN
C=TERMINAL
B= TIP SPRING
A= BODY

DC 30V 0,5A
3~20n
0,5KG ~ 3,5KG
500 VOLTS
5000 cycles
FROM -30°C TO +70°C
FROM 40% TO 85%
HUMIDITY 90% TO 95% TEMPERATURE 40°C +/- 2°C F. 96 HRS
TEMPERATURE 70°C +/- 2°C V (HUMIDITY BELOW 50% F. 96HRS
. +/-2°C FOR 96 HOURS
THE TERMINATION IS AT LEAST 96% COVERD BY A CONTINUOUS NEW SOLDER COATING
DIP SOLDER FOR 5 SEC AT 245°C +/- 5°C TERMINATION SHAL BE IMMERSIED IN FLUX BEFORE TEST
LEAD FREE PROCESS

STAINLESS 0,1T
BRASS STRIP 0,3T NI 60µ
BRASS BAR NI 60µ
BRASS STRIP 0,3T AG 20µ OVER NI 20µ
COPPER ALLOY 0,3T AG20µ OVER NI 20µ
HIGH TEMPERATURE THERMOPLASTIC UL 94V-0 BLACK

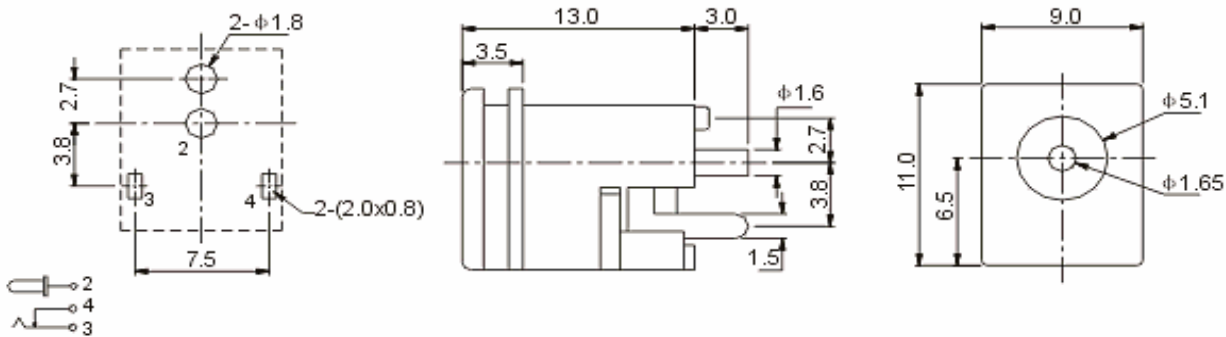
THT DC-POWER JACK	
Part No.:	<b>T19B065</b>
Customer:	

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	DATE	06.05.2007
APPD:	Schumi			FINISH	Jamy	Sheet	1 from 3

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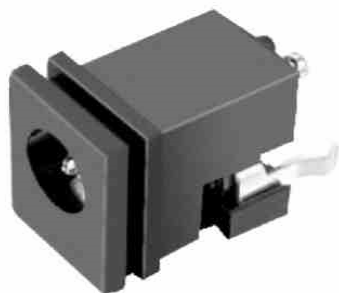
## Technical Drawing:



THT DC-POWER JACK	
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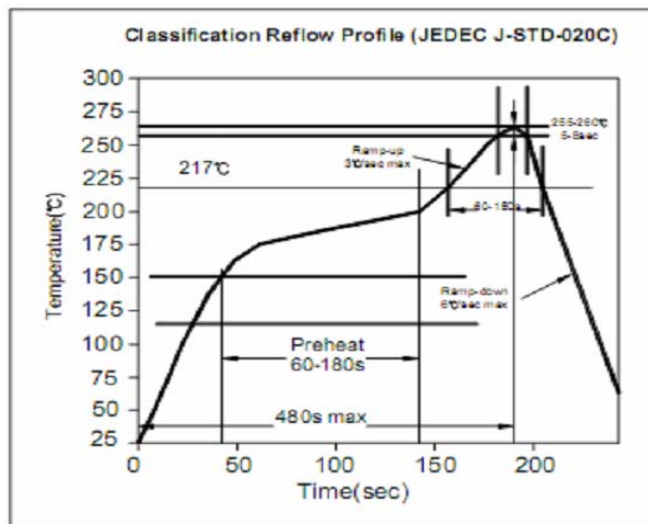


## Solder Profile

### Lead Solder



### Lead Free Solder



## Ordering Informations:

Item-No.	Pin Diameter	ROHS	Packing			
<b>T19B065</b>	<b>A</b>	<b>R</b>	<b>BU</b>			

<b>A= 1,65mm</b>	<b>R= ROHS</b>	<b>BU= Bulk (Standard)</b>
	<b>N= Non ROHS</b>	<b>TR= Tape/Reel</b>
		<b>TR= Tray Packing</b>

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